

IN THE CLAIMS

Please amend the claims as follows.

1. - 17. (Canceled)

18. (Currently Amended) An apparatus for manufacturing a semiconductor device, comprising:

- a stage to hold a semiconductor wafer during processing;
- an exposure slit positioned relative to the stage;
- projection optics to focus a light beam through the exposure slit and onto a selected portion of the semiconductor wafer;
- at least one vacuum tube adjacent the exposure slit; and
- a single no more than one opening formed in the vacuum tube at a selected location to cause air flow in the exposure slit away from a lens of the projection optics.

19. (Currently Amended) The apparatus of claim 18, wherein the selected location of the single no more than one opening is at about a mid-point of the exposure slit.

20. (Currently Amended) The apparatus of claim 18, wherein the single no more than one opening has a predetermined size and shape.

21. (Currently Amended) ~~The apparatus of claim 18, further comprising~~ An apparatus for manufacturing a semiconductor device, comprising:

- a stage to hold a semiconductor wafer during processing;
- an exposure slit positioned relative to the stage;
- projection optics to focus a light beam through the exposure slit and onto a selected portion of the semiconductor wafer;
- at least one vacuum tube adjacent the exposure slit;
- a single opening formed in the vacuum tube at a selected location to cause air flow in the exposure slit away from a lens of the projection optics;
- a second vacuum tube adjacent the exposure slit on an opposite side of the exposure slit from the at least one vacuum tube; and
- a single opening formed in the second vacuum tube at a selected location.

22. (Original) The apparatus of claim 21, wherein the selected location of each single openings is at about a mid-point of the exposure slit.

23. (Original) The apparatus of claim 21, wherein the selected location of the single openings causes a maximum reduction of outgassed particles from contaminating the lens.

24. (Currently Amended) A method of making a vacuum debris removal system, comprising:
providing at least one vacuum tube; and
forming ~~a single~~ no more than one opening in the at least one vacuum tube at a selected location to cause air flow away from ~~an~~ a lens element of an integrated circuit manufacturing device.

25. (Currently Amended) The method of claim 24, further comprising forming the ~~single~~ no more than one opening to have a predetermined size and shape.

26. (Currently Amended) The method of claim 24, further comprising selecting the location to form the ~~single~~ no more than one opening to be at about a mid-point of an exposure slit of the integrated circuit manufacturing device.

27. (Currently Amended) ~~The method of claim 24, further comprising:~~ A method of making a vacuum debris removal system, comprising:
providing at least one vacuum tube;
forming a single opening in the at least one vacuum tube at a selected location to
cause air flow away from an element of an integrated circuit manufacturing device;
disposing the at least one vacuum tube on one side of an exposure slit of the integrated circuit manufacturing device;
disposing a second vacuum tube on an opposite side of the exposure slit; and
forming a single hole in the second vacuum tube to cause air flow in the exposure slit away from the element of the integrated circuit manufacturing device.

AMENDMENT UNDER 37 C.F.R. 1.116 – EXPEDITED PROCEDURE

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Title: VACUUM DEBRIS REMOVAL SYSTEM FOR AN INTEGRATED CIRCUIT MANUFACTURING DEVICE

Assignee: Intel Corporation

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28. - 31. (Canceled)

32. (New) The method of claim 27, further comprising forming the single opening to have a predetermined size and shape.